

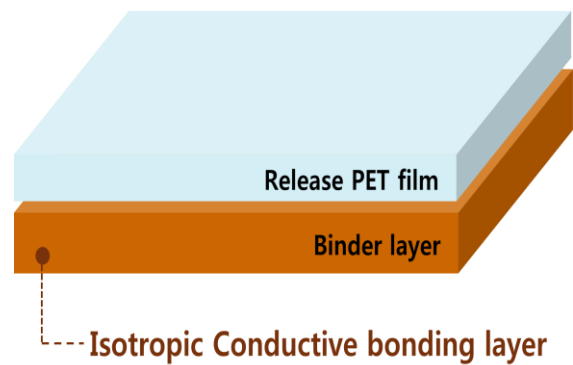
► Description

ICB series is a thermosetting conductive bonding Film. It interconnects GND on FPCB and metallic stiffener and it can strengthen GND interconnection



<Fig 1 ICB series film>

► Construction



<Fig 2 ICB series Film Construction>

Protect Film	Release PET
ICB* Layer	Modified Resin Based (with metal filler)

*ICB is *abbr.* of Isotropic Conductive Adhesive.

► Application

Camera module

(mobile phone, game machine, laptop, etc).



<Fig 3 ICB Film Application>

Features of ICB series Film

- Strengthening GND
- Applicable to Pb-free reflow-solder
- Outstanding adhesion to stiffener (SUS, PI, FR-4)
- Excellent conductivity based on Ag-Cu

► Typical Properties

Typical physical and electrical properties along with applicable test methods are shown in Table.

Properties		Unit	ICB-100	ICB-200	Test Method
Thickness	Protective film(release film)	μm	75±5	75±5	Micrometer
	Conductive Adhesive Layer(ICB)	μm	40±3	60±3	Micrometer
Linear resistance		Ω/6cm	0.8	0.5	HIOKI 3244-60 (3cm, 2mm Φ)
Surface Resistance		Ω/□	0.3	0.16	Four point probe sheet Resistance measurement
Peel	ICB-Coverlay PI side	Kgf/10mm	>1.0	>1.0	UTM (50mm/min speed, angle 180)
	ICB- Cu side (Shiny)	Kgf/10mm	>1.0	>1.0	UTM (50mm/min speed, angle 180)

► Packing

- Product Width: 250mm or 500mm Rolls
- Film Length: Controllable as customer's request

► Storage Warning & Shelf Life

- Store it in low temperature & humidity (temp.: 5±3 °C/ humidity: 40±10%) away from direct sunshine.
- Allow the refrigerated film with plastic wrap to stand at room temperature before using it. (By doing this, you can avoid deterioration from Dew condensation.
- Avoid treating products with bare hands. Put on the clean gloves while handling the products.
- Be careful not to drop the roll and keep it away from a shock.

► Standard Processing

1. Cut out wanted size.
 2. Pre-fixing on the cover-lay film.(130~150 °C)
 3. Thermal Pressing.
(160±10 °C, Max 3MPa, 50±10min)
[Quick Press ; : 170 °C, 4MPa, 60s / 150 °C 20min]
- *Do not increase the Pressure over than 3.0MPa in order to prevent Resin Flow

► Using Warning

- Avoid treating products with bare hands during operation.
- During thermal processing, be careful not to contact the hot press machine.
- Please be careful not getting foreign substances on the adhesive layer, when pre-fixing Process.